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Semiconductor devices - Mechanical and climatic test methods - Part 15:  
Resistance to soldering temperature for through-hole mounted devices (IEC 60749-  
15:2003)

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[SIST EN 60749-15:2004](https://standards.iteh.ai/catalog/standards/sist/96cd45d3-f60d-4230-a018-04338b701d23/sist-en-60749-15-2004)  
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English version

**Semiconductor devices –  
Mechanical and climatic test methods  
Part 15: Resistance to soldering temperature  
for through-hole mounted devices  
(IEC 60749-15:2003)**

Dispositifs à semiconducteurs –  
Méthodes d'essais mécaniques  
et climatiques  
Partie 15: Résistance à la température  
de soudage pour dispositifs  
par trous traversants  
(CEI 60749-15:2003)

Halbleiterbauelemente –  
Mechanische und klimatische  
Prüfverfahren  
Teil 15: Beständigkeit gegen  
Löttemperatur bei Bauelementen  
zur Durchsteckmontage  
(IEC 60749-15:2003)

<https://standards.iteh.ai/catalog/standards/sist/96cd45d3-f60d-4230-a018-344970223164/iec-60749-15-2003>

This European Standard was approved by CENELEC on 2003-04-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Slovakia, Spain, Sweden, Switzerland and United Kingdom.

## CENELEC

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## Foreword

The text of document 47/1663/FDIS, future edition 1 of IEC 60749-15, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-15 on 2003-04-01.

This mechanical and climatic test method, as it relates to resistance to soldering temperature for through-hole mounted devices, is a complete rewrite of the test contained in Subclause 2.2, Chapter 2 of EN 60749:1999.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2004-01-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2006-04-01

Annexes designated "normative" are part of the body of the standard.  
In this standard, annex ZA is normative.  
Annex ZA has been added by CENELEC.

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**Endorsement notice**

SIST EN 60749-15:2004  
The text of the International Standard IEC 60749-15:2003 was approved by CENELEC as a European Standard without any modification.  
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**Annex ZA**  
(normative)

**Normative references to international publications  
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-20	- 1)	Basic environmental testing procedures Part 2: Tests - Test T: Soldering	HD 323.2.20 S3	1988 2)

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1) Undated reference.

2) Valid edition at date of issue.

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NORME  
INTERNATIONALE  
INTERNATIONAL  
STANDARD

CEI  
IEC

60749-15

Première édition  
First edition  
2003-02

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**Dispositifs à semiconducteurs –  
Méthodes d'essais mécaniques et climatiques –**

**Partie 15:  
Résistance à la température de soudage  
pour dispositifs par trous traversants**

(standards.iteh.ai)

**Semiconductor devices –  
Mechanical and climatic test methods –**

**Part 15:  
Resistance to soldering temperature  
for through-hole mounted devices**

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Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

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For price, see current catalogue*

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –**
**Part 15: Resistance to soldering temperature  
for through-hole mounted devices**

## FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60749-15 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1663/FDIS	47/1683/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This mechanical and climatic test method, as it relates to resistance to soldering temperature for through-hole mounted devices, is a complete rewrite of the test contained in subclause 2.2 of chapter 2 of IEC 60749.



The committee has decided that the contents of this publication will remain unchanged until 2007. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

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